

Product Change Notification

(Notification - P1705030-DIGI)

May 24, 2017

To: Our Valued Digi-Key Electronics Customer

Overview: The purpose of this notification is to communicate a product change of select Renesas Electronics America, Inc. (REA) devices. These devices have suggested replacements.

Select power devices are changing assembly and test sites from SP Semiconductors Pvt. Ltd. (SP, Korea) to Advanced Semiconductor Engineering, Inc. (ASE, China / Weihai).

There are no changes to electrical characteristics or reliability levels.

The new replacement devices will change the outline, packing, and markings. See the appendix for additional details.

Affected Products: A review of our records indicate the list of products below may affect your company.

Booking Part Number	Suggested Replacement Part Number
BCR16FM-14LB#FA0	BCR16FM-14LB#FG0
BCR3FM-12RB#GA1	BCR3FM-12RB#GG1
BCR8FM-14LB#FA0	BCR8FM-14LB#FG0
RJK5034DPP-E0#T2	RJK5034DPP-A0#T2
RJK5035DPP-E0#T2	RJK5035DPP-A0#T2
RJK6006DPP-E0#T2	RJK6006DPP-A0#T2
RJK6012DPP-E0#T2	RJK6012DPP-A0#T2
RJK6035DPP-E0#T2	RJK6035DPP-A0#T2
RJU6052TDPP-EJ#T2	RJU6052TDPP-AJ#T2
RJU6053TDPP-EJ#T2	RJU6053TDPP-AJ#T2
RJU6054TDPP-EJ#T2	RJU6054TDPP-AJ#T2
RJU60C3TDPP-EJ#T2	RJU60C3TDPP-AJ#T2

Part numbers given in this list are for active part numbers in REA database at the time of this notification.

Key Dates:

Availability of samples of replacement devices	Jun. 15 th , 2017
Final last time buy (LTB) orders of original part number placed to REA or to a franchised REA distributor.	Jun. 15 th , 2018
Planned date for last time shipment (LTS) of original part number from REA.	Dec. 15 th , 2018

Response:

Please switch to replacement device as soon as possible to avoid disruption of supply. Place last time buy (LTB) orders in a timely manner prior to the key dates listed to avoid product availability issues. If you anticipate volumes beyond your regular rate, please contact your REA sales representative with a forecast of your requirements. Shipments between the LTB and LTS dates are Non-Cancelable and Non-Returnable (NCNR).

Please contact your REA sales representative for any questions or comments.

Thank you for your attention.

Sincerely,

Renesas Electronics America, Inc.



Appendix A: Change Details

Item	Current	New	Other
Facility	SP	ASE	
Material			Same type of material
- Die attach	Solder	Solder	
- Frame	Cu	Cu	
- Mold resin	Epoxy resin	Epoxy resin	
Operator	Employee of SP	Employee of ASE	
Machine			· Same process and
- Dicing	Cutting	Cutting	similar machine are used.
- Die bonding	Soldering die bonder	Soldering die bonder	
- Wire bonding	Ultra sonic bonding	Ultra sonic bonding	
- Molding	Transfer molding	Transfer molding	
- Plating	Sn plating	Sn plating	
- Test	TRS tester	TRS tester	

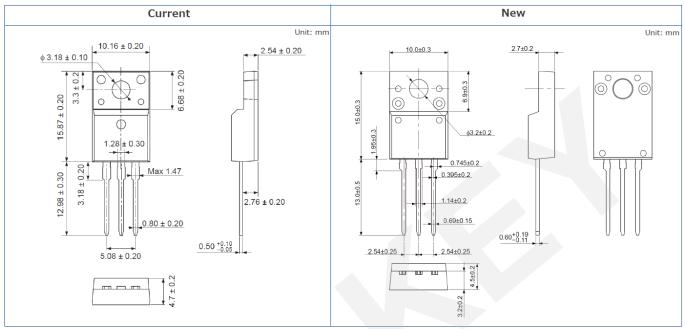
Appendix B: Process Flow

Current		New	
Process flow	QC item	Process flow	QC item
Dicing Die bonding Wire bonding Molding Cut and form Mark Electrical test Packing	Visual, Force Visual, Force Visual Visual Electrical Lead forming*	Dicing Die bonding Wire bonding Molding Cut and form Mark Electrical test Packing	Visual, Force Visual, Force Visual Visual Electrical Lead forming*
Shipping		Shipping	

^{*} Lead forming type product will be the same as the current product.

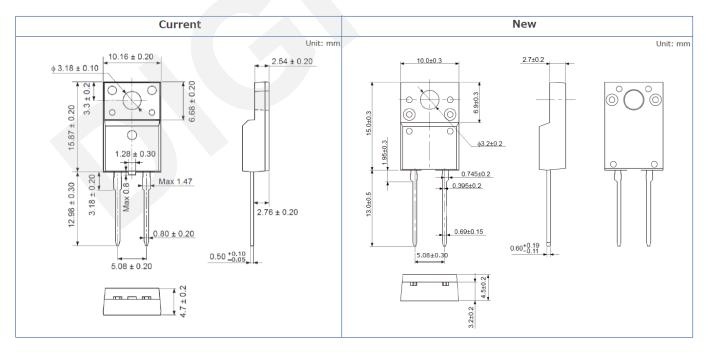


Appendix C: Outline Dimension (3pin)



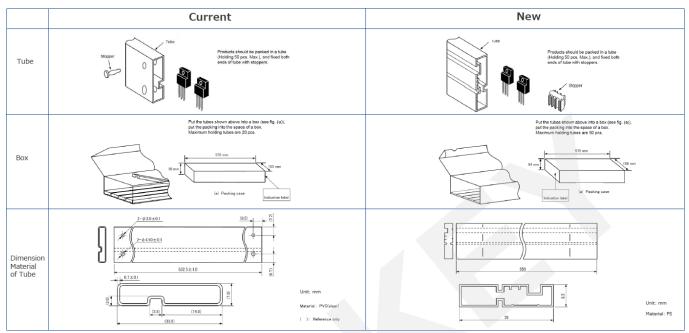
^{*} This outline dimension is for the straight lead type. For the lead forming type, please contact us.

Appendix D: Outline Dimension (2pin)



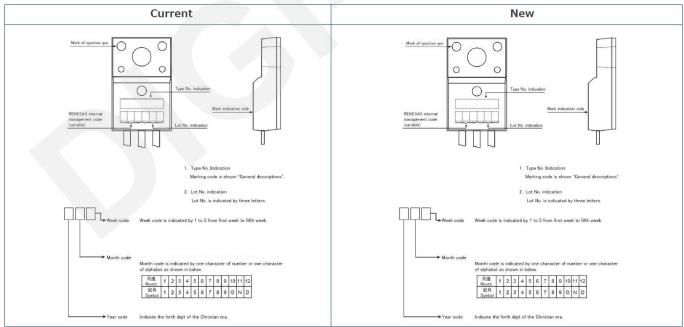


Appendix E: Packing Dimension (3pin & 2pin)



^{*} This outline dimension is for the straight lead type. For the lead forming type, please contact us.

Appendix F: Marking (MOSFET, IGBT & FRD) (3pin & 2pin)



^{*} The marking does not change for MOSFET, IGBT and FRD.



Appendix G: Marking (Triac)

